

PROTECTION PRODUCTS
Absolute Maximum Rating

Rating	Symbol	Value	Units
Peak Pulse Power (tp = 8/20μs)	P_{pk}	75	Watts
Peak Pulse Current (tp = 8/20μs)	I_{pp}	5	A
ESD per IEC 61000-4-2 (Air) ESD per IEC 61000-4-2 (Contact)	V_{ESD}	+/- 30 +/- 25	kV
Operating Temperature	T_J	-40 to +125	°C
Storage Temperature	T_{STG}	-55 to +150	°C

Electrical Characteristics (T=25°C Unless Otherwise Specified)

Parameter	Symbol	Conditions	Minimum	Typical	Maximum	Units
Reverse Stand-Off Voltage	V_{RWM}	Any I/O to GND			3.3	V
Punch-Through Voltage	V_{PT}	$I_{PT} = 2\mu A$ Any I/O to GND	3.8	4.8	5.5	V
Reverse Leakage Current	I_R	$V_{RWM} = 3.3V$ Any I/O to GND		0.005	0.100	μA
Clamping Voltage	V_C	$I_{pp} = 1A$, tp = 8/20μs Any I/O to GND			7	V
Clamping Voltage	V_C	$I_{pp} = 5A$, tp = 8/20μs Any I/O to GND			10.5	V
Junction Capacitance	C_J	$V_R = 0V$, f = 1MHz, Any I/O to GND		0.40	0.65	pF
		$V_R = 0V$, f = 1MHz, Between I/O pins		0.30	0.4	pF

PROTECTION PRODUCTS

Electrical Characteristics (T=25°C Unless Otherwise Noted)

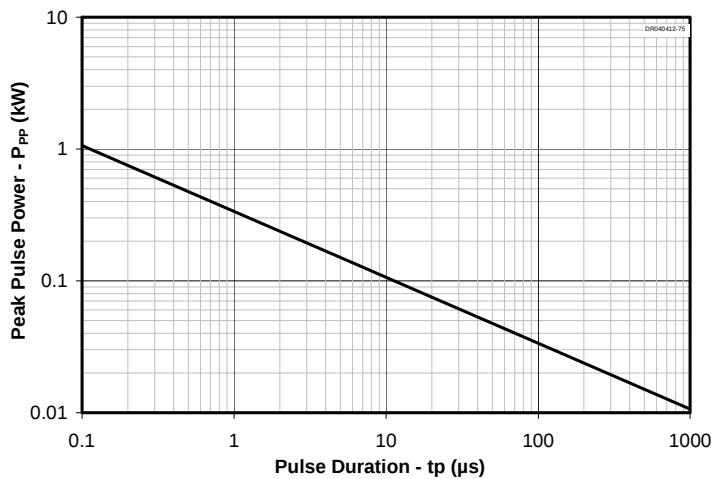
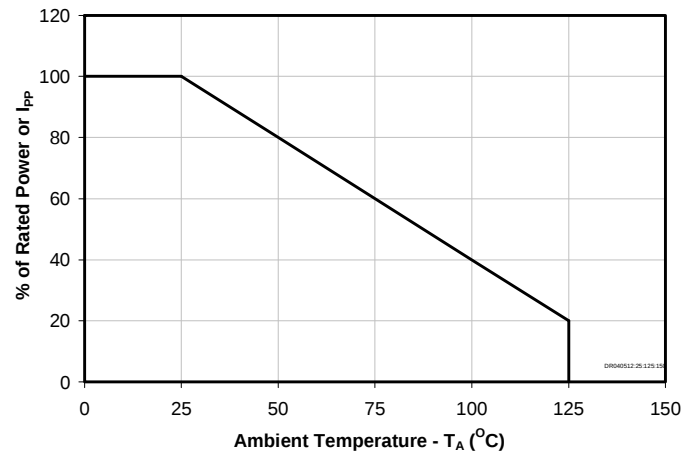
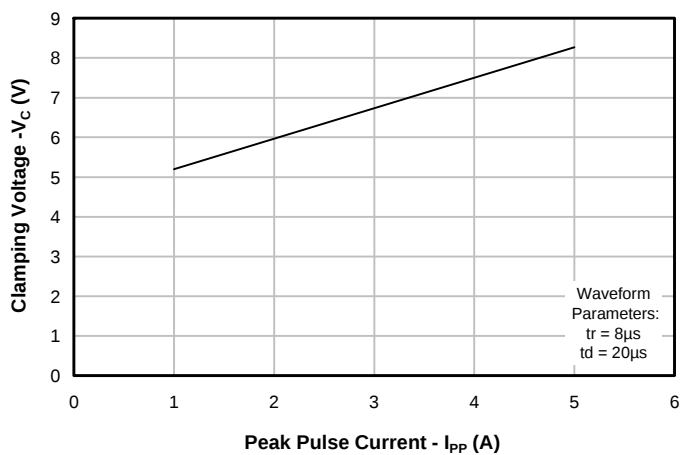
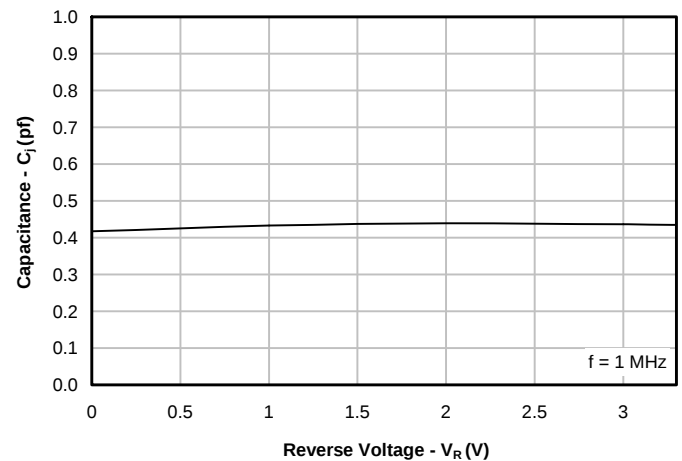
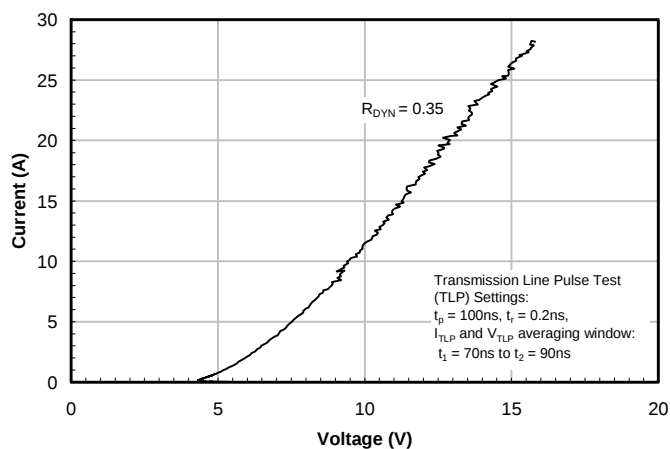
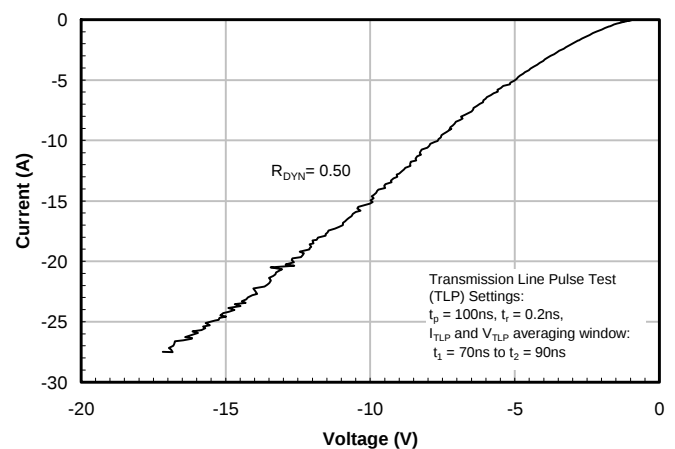
ESD Ratings (Each Pin)						
Parameter	Symbol	Conditions	Minimum	Typical	Maximum	Units
ESD Withstand Voltage ¹		Contact discharge per IEC 61000-4-2			25	kV
ESD Withstand Voltage ¹		Air discharge per IEC 61000-4-2			30	kV
ESD Peak Voltage ¹	V_{pk}	+8kV per IEC 61000-4-2		55		V
ESD Peak Voltage ¹	V_{pk}	-8kV per IEC 61000-4-2		-60		V
ESD Clamping Voltage ²	V_{t1p}	$I_{pp} = 16A$, $t1p = 0.2/100ns$		11.5		V
ESD Clamping Voltage ²	V_{t1p}	$I_{pp} = -16A$, $t1p = 0.2/100ns$		11		V
Dynamic Resistance (Positive) ^{2, 3}	R_{dyn}	$t_p = 100ns$		0.35		Ohms
Dynamic Resistance (Negative) ^{2, 3}	R_{dyn}	$t_p = 100ns$		0.50		Ohms

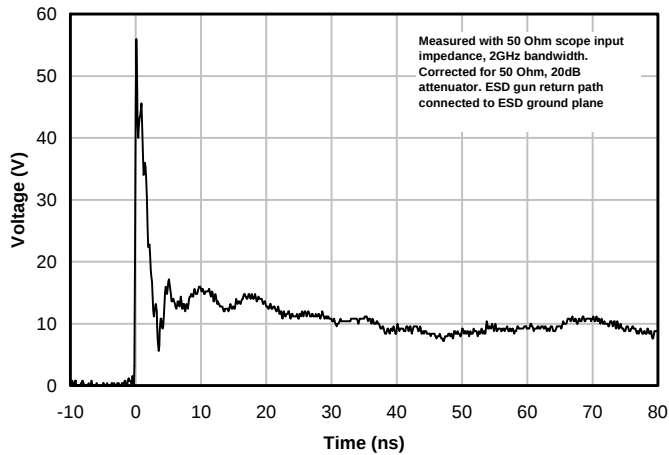
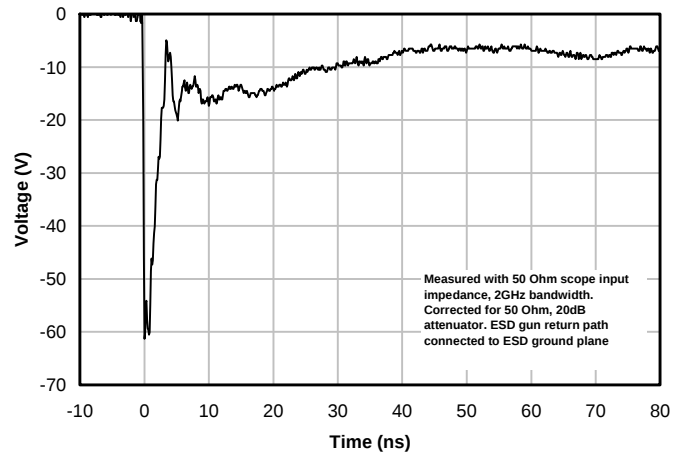
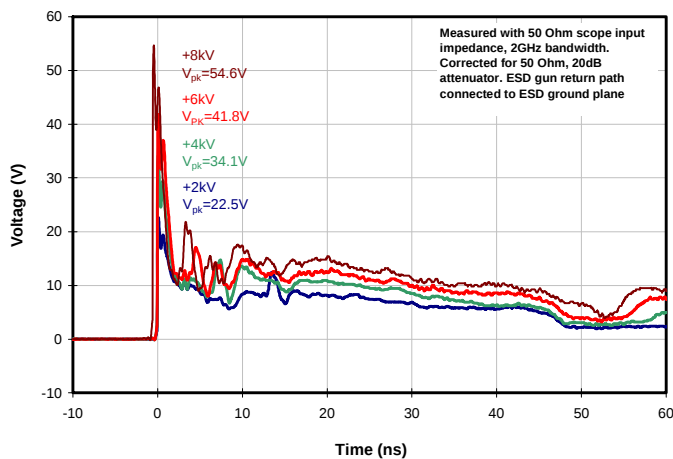
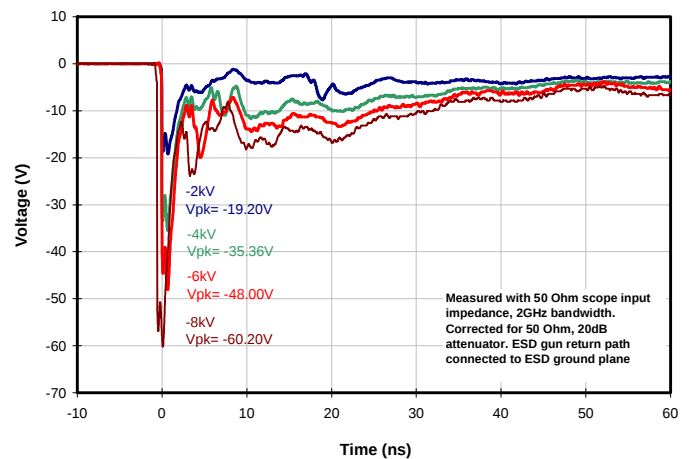
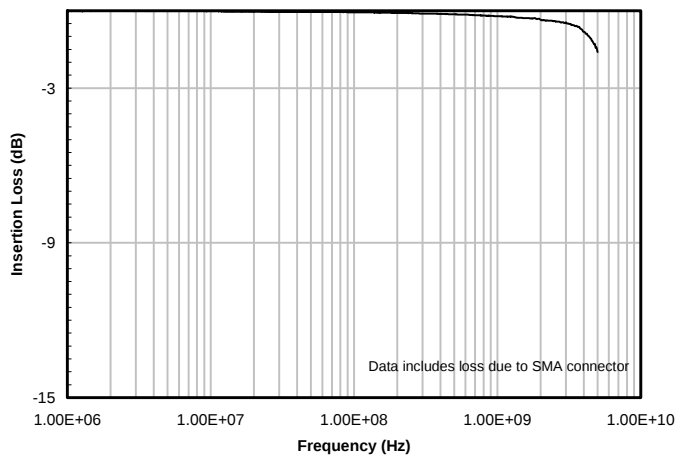
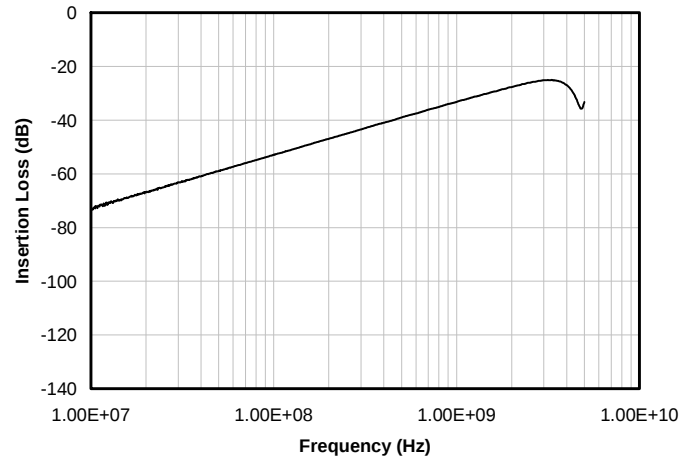
Notes

1)ESD peak voltage measured with a 20dB attenuator, 50 Ohm scope input impedance, 2GHz bandwidth. ESD gun return path connected to ESD ground plane.

2)Transmission Line Pulse Test (TLP) Settings: $t_p = 100ns$, $t_r = 0.2ns$, I_{TLP} and V_{TLP} averaging window: $t_1 = 70ns$ to $t_2 = 90ns$.

3) Dynamic resistance calculated from $I_{TLP} = 4A$ to $I_{TLP} = 16A$

PROTECTION PRODUCTS
Typical Characteristics
Non-Repetitive Peak Pulse Power vs. Pulse Time

Power Derating Curve

Clamping Voltage vs. Peak Pulse Current

Capacitance vs. Reverse Voltage

TLP Characteristic (Positive Pulse)

TLP Characteristic (Negative Pulse)


PROTECTION PRODUCTS
Typical Characteristics
**ESD Clamping at Each Pin
(+8kV Contact per IEC 61000-4-2)**

**ESD Clamping at Each Pin
(-8kV Contact per IEC 61000-4-2)**

**ESD Clamping vs. Positive Discharge Voltage
(Contact Discharge per IEC 61000-4-2)**

**ESD Clamping vs. Negative Discharge Voltage
(Contact Discharge per IEC 61000-4-2)**

Typical Insertion Loss S21 (5GHzZ)

Analog Crosstalk


PROTECTION PRODUCTS
Applications Information
Layout Guidelines

RClamp3324T is designed to protect 2 high speed differential pairs. The PCB traces enter and exit each I/O pin. Ground is connected at pins 5 and 6. Figure 2 is an example of how to route the high speed differential traces through the RClamp3324T. The differential impedance of each pair can be controlled for high-speed interfaces such as HDMI (100 Ohms +/- 15%) and USB 3.0 (85 Ohms +/- 15%) while maintaining a minimum trace-to-trace and trace-to-pad spacing of 0.125mm when using 0.100mm wide traces. These are only guidelines. Individual PCB design constraints may necessitate different spacing or trace width. Both ground pads should be connected for optimal performance. Ground connection is made using 0.254mm diameter filled via-in-pad. The via should be filled with a conductive paste. This technique saves board space and eliminates the capillary effect of a non filled via.

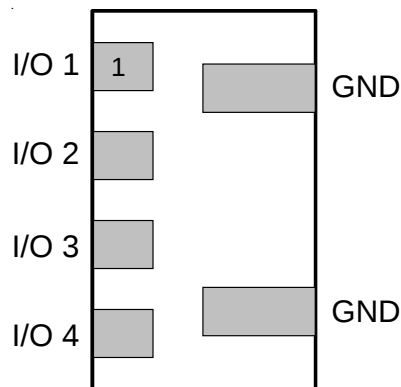


Figure 1 - Pin Configuration

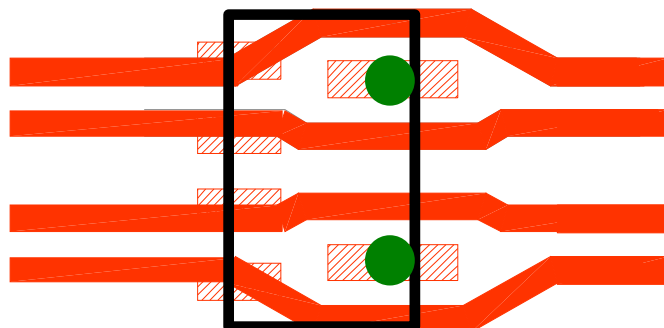
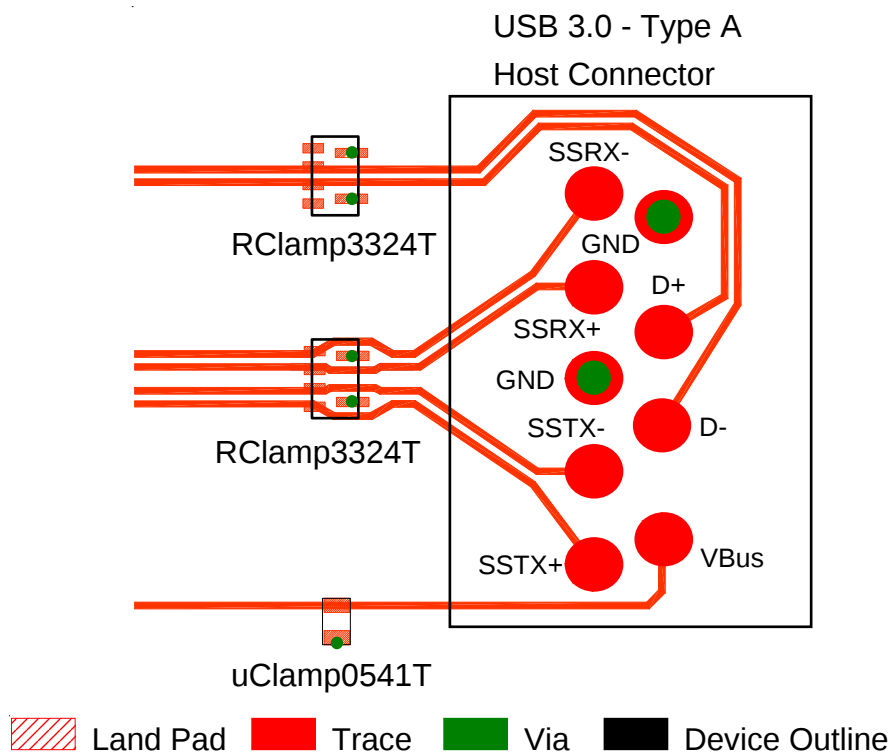
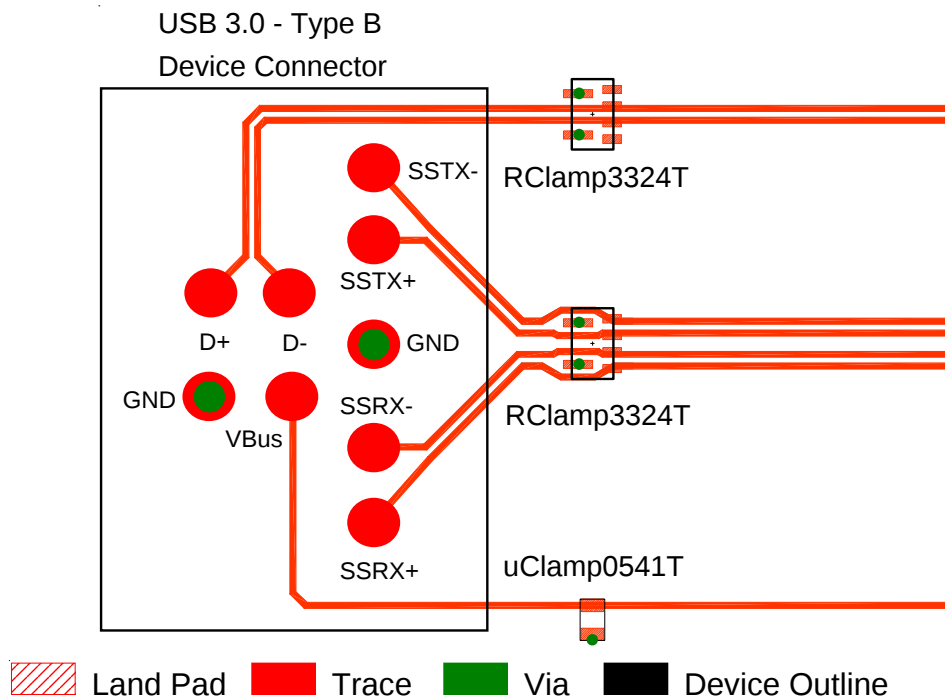
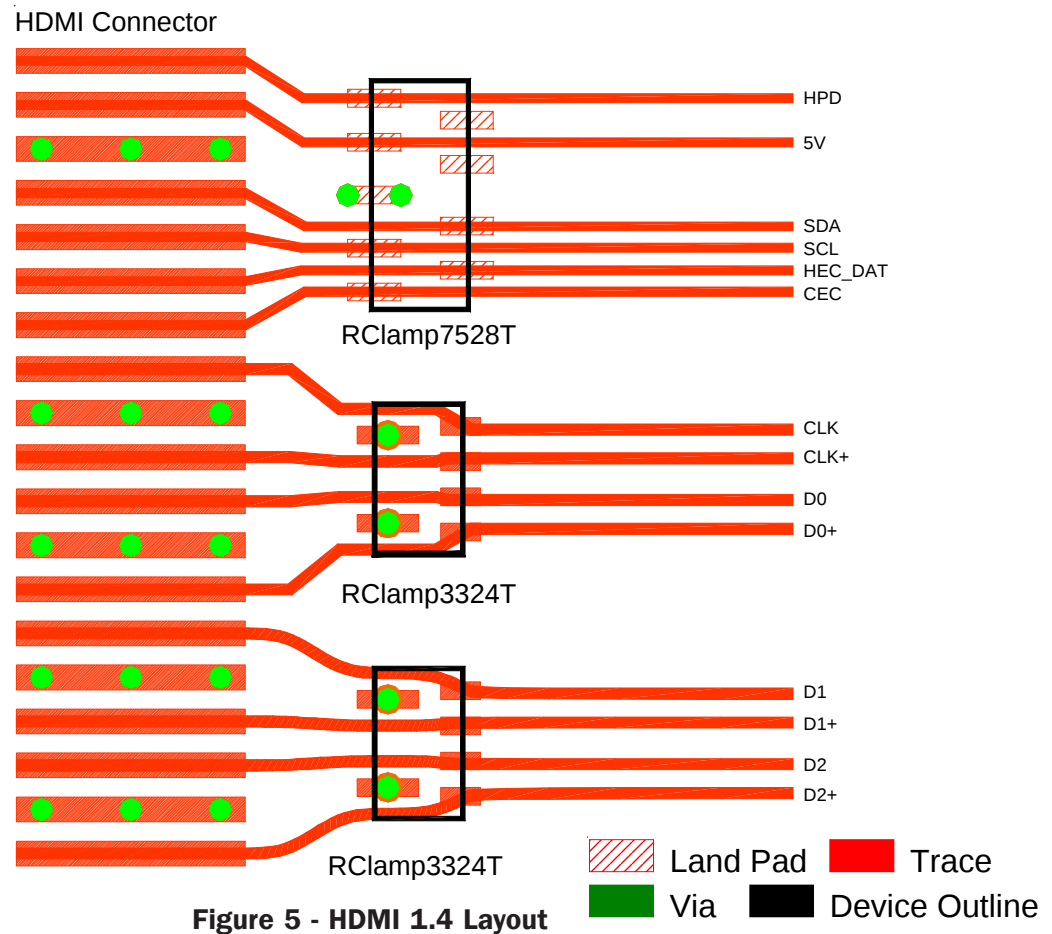


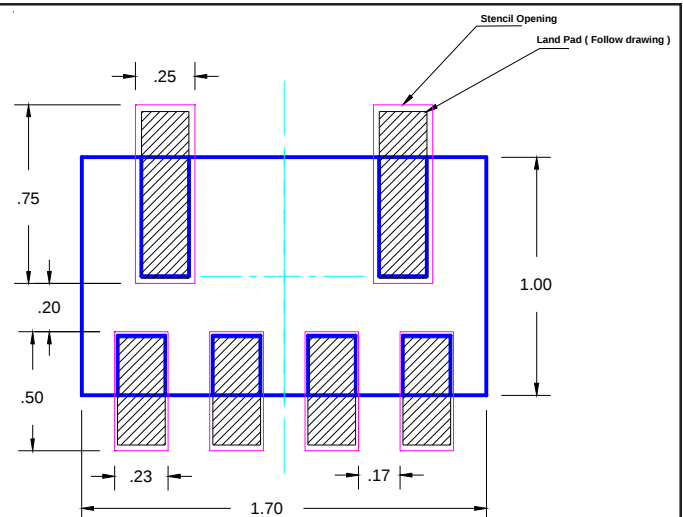
Figure 2 - Example Flow-Through Layout

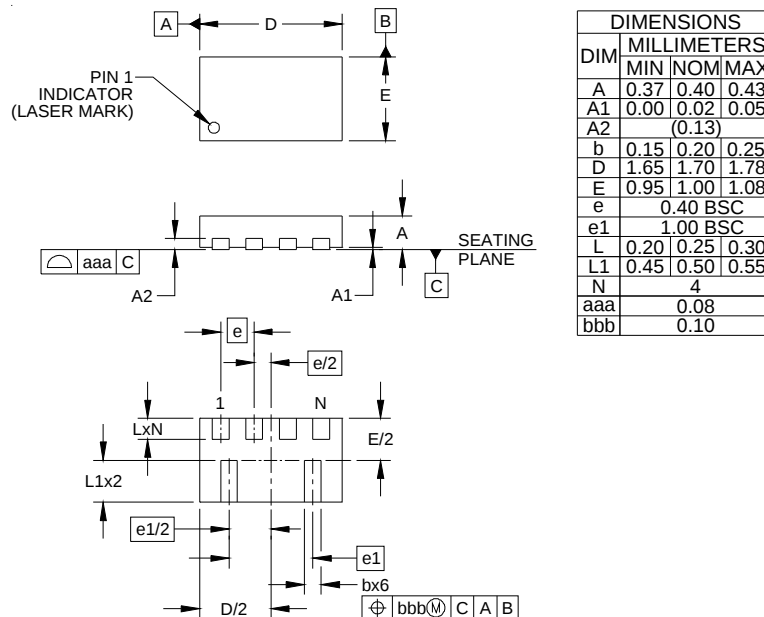
PROTECTION PRODUCTS
Applications Information

Figure 3 - USB 3.0 Layout (Type A Host Connector)

Figure 4 - USB 3.0 Layout (Type B Device Connector)

PROTECTION PRODUCTS
Applications Information

Figure 5 - HDMI 1.4 Layout
Recommended Assembly Parameters

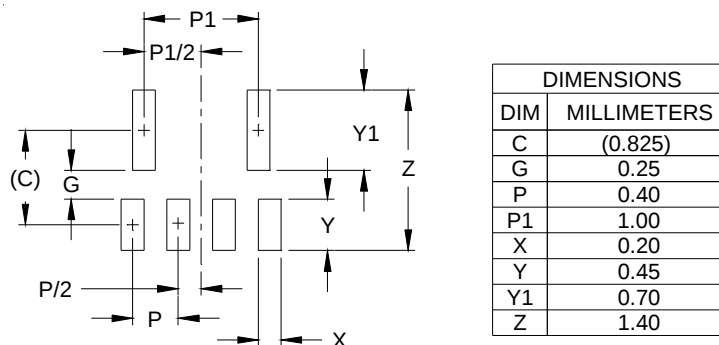
Assembly Parameter	Recommendation
Solder Stencil Design	Laser cut, Electro-polished
Aperture shape	Rectangular with rounded corners
Solder Stencil Thickness	0.100 mm (0.004")
Solder Paste Type	Type 3 size sphere or smaller
Solder Reflow Profile	Per JEDEC J-STD-020
PCB Solder Pad Design	Non-Solder mask defined
PCB Pad Finish	OSP OR NiAu

Note that these are only recommendations and should serve only as a starting point for design. The exact manufacturing parameters will require some experimentation to get the desired solder application.

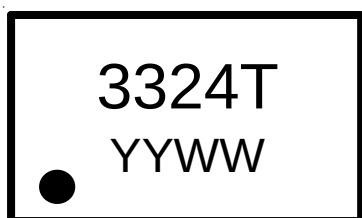

Recommended Mounting Pattern

PROTECTION PRODUCTS
Outline Drawing - SLP1710P4T

NOTES:

1. CONTROLLING DIMENSIONS ARE IN MILLIMETERS (ANGLES IN DEGREES).
2. COPLANARITY APPLIES TO THE EXPOSED PAD AS WELL AS THE TERMINALS.

Land Pattern - SLP1710P4T

NOTES:

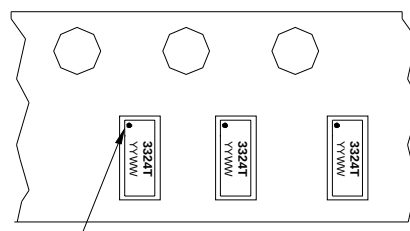
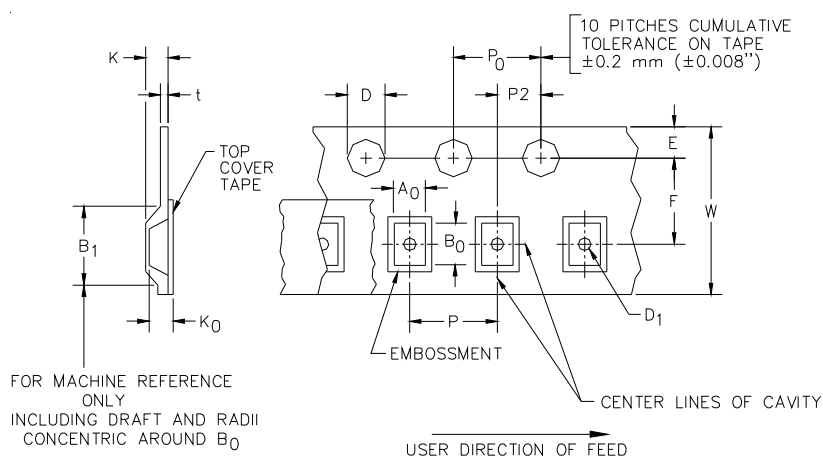
1. CONTROLLING DIMENSIONS ARE IN MILLIMETERS (ANGLES IN DEGREES).
2. THIS LAND PATTERN IS FOR REFERENCE PURPOSES ONLY. CONSULT YOUR MANUFACTURING GROUP TO ENSURE YOUR COMPANY'S MANUFACTURING GUIDELINES ARE MET.

PROTECTION PRODUCTS
Marking Codes

Ordering Information

Part Number	Qty per Reel	Reel Size
RClamp3324T.TCT	3,000	7 Inch

RailClamp and RClamp are trademarks of Semtech Corporation.

YYWW = Alphanumeric character Date Code

Carrier Tape Specification


Pin 1 Location (Towards Sprocket Holes)

User Direction of feed

A0	B0	K0
1.18 +/-0.05 mm	1.88 +/-0.05 mm	0.53 +/-0.05 mm

Device Orientation in Tape

Tape Width	B, (Max)	D	D1	E	F	K (MAX)	P	P0	P2	T(MAX)	W
8 mm	4.2 mm	1.5 + 0.1 mm - 0.0 mm)	0.5 mm ±0.05	1.750±10 mm	3.5±0.05 mm	2.4 mm	4.0±0.1 mm	4.0±0.1 mm	2.0±0.05 mm	0.4 mm	8.0 mm + 0.3 mm - 0.1 mm

Contact Information

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